



Material Content Data Sheet



Sales Product Name		SPD06N60C3		Issued		20. July 2018		
MA#		MA001684760						
Package		PG-TO252-3-341		Weight*		382.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.096	1.07	1.07	10697	10697
leadframe	inorganic material	phosphorus	7723-14-0	0.075	0.02		195	
	non noble metal	iron	7439-89-6	0.248	0.06		649	
	non noble metal	copper	7440-50-8	248.124	64.80	64.88	648061	648905
	non noble metal	aluminium	7429-90-5	0.429	0.11	0.11	1119	1119
wire	inorganic material	antimonytrioxide	1309-64-4	1.711	0.45		4468	
encapsulation	plastics	brominated resin	-	1.833	0.48		4787	
	organic material	carbon black	1333-86-4	1.955	0.51		5106	
	plastics	epoxy resin	-	16.494	4.31		43081	
	inorganic material	silicondioxide	60676-86-0	100.188	26.17	31.92	261675	319117
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9768	9768
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1329	1329
solder	non noble metal	tin	7440-31-5	0.069	0.02		181	
	noble metal	silver	7440-22-4	0.087	0.02		227	
	non noble metal	lead	7439-92-1	3.315	0.87	0.91	8657	9065
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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